



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D

*\* : Required Field*

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2015-06-25
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	IPD MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.


**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
------------------------------	------	----------------------------	----------

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	R1DZ*UM7GB61	A	BOUSKOURA B/E	2015-06-25
Amount	UoM	Unit type	ST ECOPACK Grade	
1900	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10, 9.1, 4.5	3	THROUGH HOLE	
Comment	Package: TO 220 AB NON ISOL, MD valid for CP:STP65NF06, STP80N70F4.			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2014				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	RID2*UM7GB61					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies (choose)	Other inorganic materials	7.685	mg	supplier	die	Silicon (Si)	7440-21-3		7.518	mg	978269	3957
				supplier	metallization	Aluminium (Al)	7429-90-5		0.070	mg	9109	37
				supplier	Passivation	Silicon Oxide	7631-86-9		0.031	mg	4034	16
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.004	mg	520	2
				supplier	back side metallization	Gold (Au)	7440-57-5		0.011	mg	1431	6
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.051	mg	6636	27
Leadframe	Copper & its alloys	1253.179	mg	supplier	alloy	Copper (Cu)	7440-50-8		1251.376	mg	998561	658619
				supplier	alloy	Iron (Fe)	7439-89-6		1.253	mg	1000	659
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.376	mg	300	198
				supplier	metallization	Nickel (Ni)	7440-02-0		0.173	mg	138	91
				supplier	metallization	Phosphorus (P)	12185-10-3		0.001	mg	1	1
Soft solder	Solder	7.185	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	6.861	mg	954906	3611
				supplier	solder	Silver (Ag)	7440-22-4		0.180	mg	25052	95
				supplier	solder	Tin (Sn)	7440-31-5		0.144	mg	20042	76
Bonding wires	Other inorganic materials	0.127	mg	supplier	wire	Aluminium (Al)	7429-90-5		0.126	mg	992126	66
				supplier	wire	Magnesium (Mg)	7439-95-4		0.001	mg	7874	1
Bonding Ribbons	Other Nonferrous metals & alloys	4.041	mg	supplier	Ribbon	Aluminium (Al)	7429-90-5		4.041	mg	1000000	2127
Encapsulation	Other Organic Materials	621.421	mg	supplier	mold compound	Silica, vitreous	60676-86-0		540.636	mg	870000	284545
				supplier	mold compound	Epoxy resin	25068-38-6		62.142	mg	100000	32706
				supplier	mold compound	Phenol resin	29690-82-2		15.536	mg	25001	8177
				supplier	mold compound	Carbon Black	1333-86-4		3.107	mg	5000	1635
connections coating	Solder	6.362	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		6.362	mg	1000000	3348